

MATERIAL DECLARATION SHEET



Material Number	CRP0805-LF			
Product Line	High precision chip resistors			
Compliance Date	4-1-2003			
RoHS Compliant	Yes (Lead Exemption)	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic	Substrate	4.1120	Aluminum oxide	1344-28-1	96	81.075	84.453
				Silicon dioxide	7631-86-9	4	3.378	
				Magnesium oxide	1309-48-4			
2	Top conductor	Silver	0.0817	Silver	7440-22-4	100	1.678	1.678
3	Bottom conductor	Silver	0.0482	Silver	7440-22-4	100	0.990	0.990
4	Resistor	Ruthenium Oxide	0.0490	Silver	7440-22-4	40	0.402	1.006
				Ruthenium dioxide	12036-10-1	20	0.201	
				Palladium	7440-05-3	15	0.151	
				Glass	65997-18-4	13.3	0.134	
				Lead oxide	1317-36-8	11.7	0.118	

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5	First encapsulating	Resin	0.0467	Bismuth trioxide	1304-76-3	50	0.479	0.959
				Epoxy resin	25036-25-3	30	0.288	
				Aluminum oxide	1344-28-1	10	0.096	
				Boron oxide	1303-86-2	10	0.096	
6	Overcoat	Resin	0.1172	Epoxy Resin	25036-25-3	100	2.407	2.407
7	Side conductor	Silver	0.1707	Silver	7440-22-4	85	2.980	3.506
				Phenolic resin	9003-36-5	15	0.526	
8	Plating (Middle)	Nickel	0.0925	Nickel	7440-02-0	100	1.900	1.900
9	Plating (Outer)	Tin	0.1388	Tin	7440-31-5	100	2.851	2.851
10	Marking	Resin	0.0122	Epoxy Resin	25068-38-6	70	0.175	0.250
				Titanium dioxide	1317-80-2	30	0.075	
		Total weight	4.869					

This Document was updated on: 1-27-2012

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemption: 7(c)-I – electrical and electronic components containing lead in a glass or ceramic...